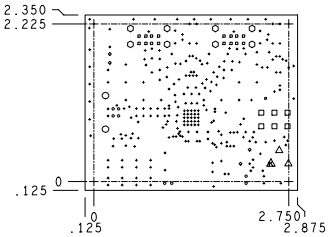
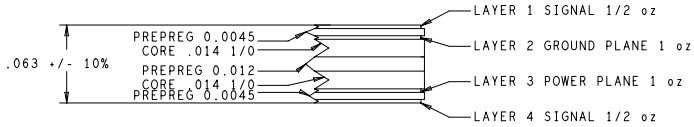
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
**	RELEASE TO MANUFACTURING	10/21/05	HJC
*A	RELEASE TO MANUFACTURING	12/07/05	HJC
*B	RELEASE TO MANUFACTURING	06/13/06	HJC
*C	RELEASE TO MANUFACTURING	09/01/06	HJC
*D	RELEASE TO MANUFACTURING	09/14/06	HJC



DRILL CHART				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	10.0	+0.003 -0.010	PLATED	247
•	20.0	0.003	PLATED	1
·	31.0	0.003	PLATED	26
▫	35.0	0.003	PLATED	16
◦	40.0	0.003	PLATED	8
◇	43.0	0.003	PLATED	4
□	70.0	0.003	PLATED	6
○	91.0	0.003	PLATED	8
○	94.0	0.003	PLATED	2
△	120.0	0.003	PLATED	2
⚠	140.0	0.003	PLATED	1
+	125.0	0.003	NON-PLATED	4

NOTES:UNLESS OTHERWISE SPECIFIED

1. MATERIAL:
   A. EPOXY GLASS LAMINATE AND PREPREG, TYPE FR-4.
   B. USE HTE COPPER 1/2 oz. COPPER FOIL EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYERS.UNLESS OTHERWISE SPECIFIED IN STACK VIEW.
   C. OVERALL METAL TO METAL THICKNESS .063 +/- 10%
2. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
3. PLATING:
   A. COPPER PLATING IN THRU-HOLES .001 min.
4. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARYSIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATIOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
5. FINAL FABRICATION:
   A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1 SOLDERMASK COLOR **GREEN**.
6. WHEN REQUIRED, COPPER FINISH SHALL BE FINISHED TIN-LEAD (60-40 MIN) HASL.
7. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENTIFICATION. FLAMABILITY RATING (94-VO). AND DATE CODE (WWYY).
8. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMACE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
9 MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.



NOTE: 7 MIL 7 MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 100 OHMS +/- 10% TESTED

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES	DRAWN ZMK	10/19/05
TOLERANCES ON: ANGLES +/- 2°	CHECKED HJC	09/14/06
2 PL DECIMALS +/- .010	ENGRG HJC	10/21/05
3 PL DECIMALS +/- .005	ISSUED	
THIRD ANGLE PROJECTIONS		

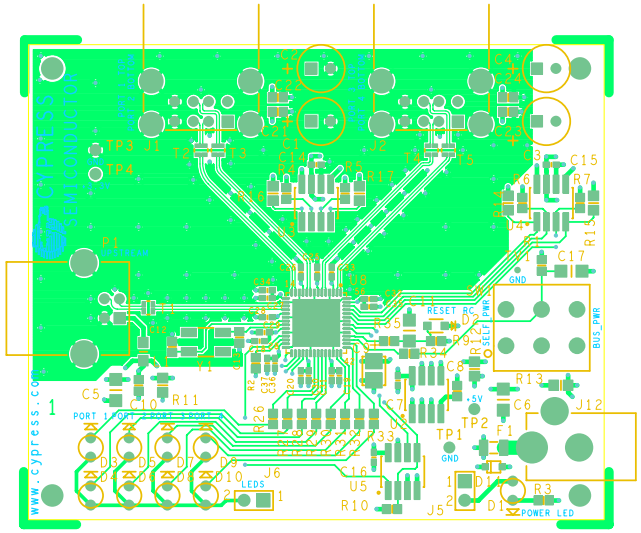
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FABRICATION DRAWING HX2LP USB 2.0 HUB REFERENCE DESIGN

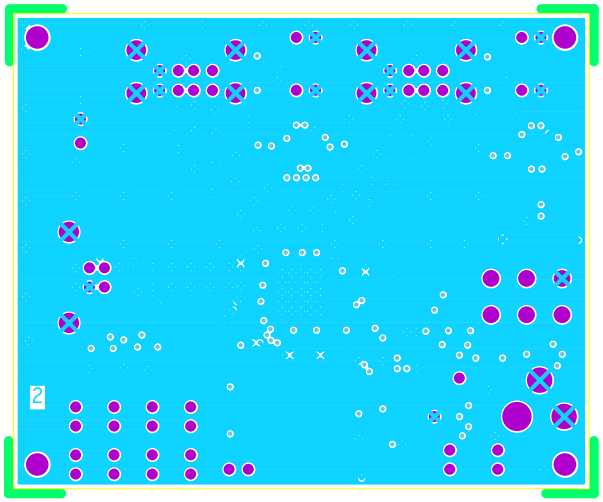
SIZE	FSCM NO	DWG NO	REV
C		PDC-9281	*D

SCALE: 1/1 SHEET: 1 OF 1

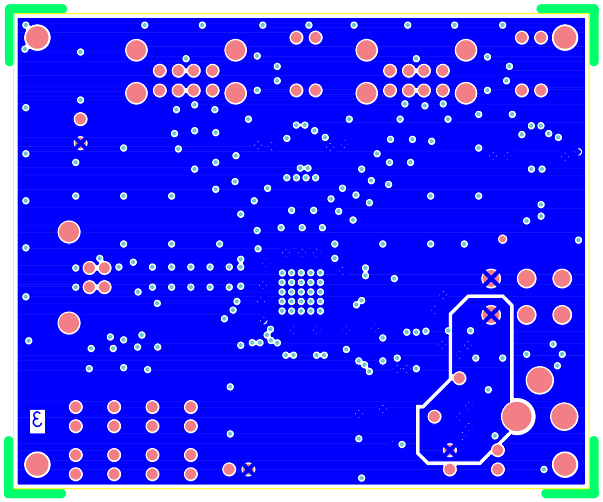


PDC-9281 REV *D PRIMARY SIDE

PDC-9281 REV *D PRIMARY SILKSCREEN



PDC-9281 REV *D LAYER 2 GND



PDC-9281 REV *D LAYER 3 VCC

PDC-9281 REV *D SECONDARY SIDE

PDC-9281 REV *D SECONDARY SILKSCREEN